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(12) **United States Design Patent** (10) **Patent No.: US D604,705 S**
Wu et al. (45) **Date of Patent: ** Nov. 24, 2009**

(54) **HEAT DISSIPATION DEVICE**

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(73) Assignee: **Foxconn Technology Co., Ltd.**, Tu-Cheng, Taipei Hsien (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/324,573**

(22) Filed: **Sep. 15, 2008**

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Classification Search** D13/179; 165/80.3, 104.33, 151, 122, 185; 257/706, 257/707, 718–722; 361/687, 695, 697, 700, 361/702, 704, 709, 710, 711, 719
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat dissipation device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a heat dissipation device showing our new design.

FIG. **2** is a front elevational view thereof.

FIG. **3** is a rear elevational view thereof.

FIG. **4** is a left-side, elevational view thereof.

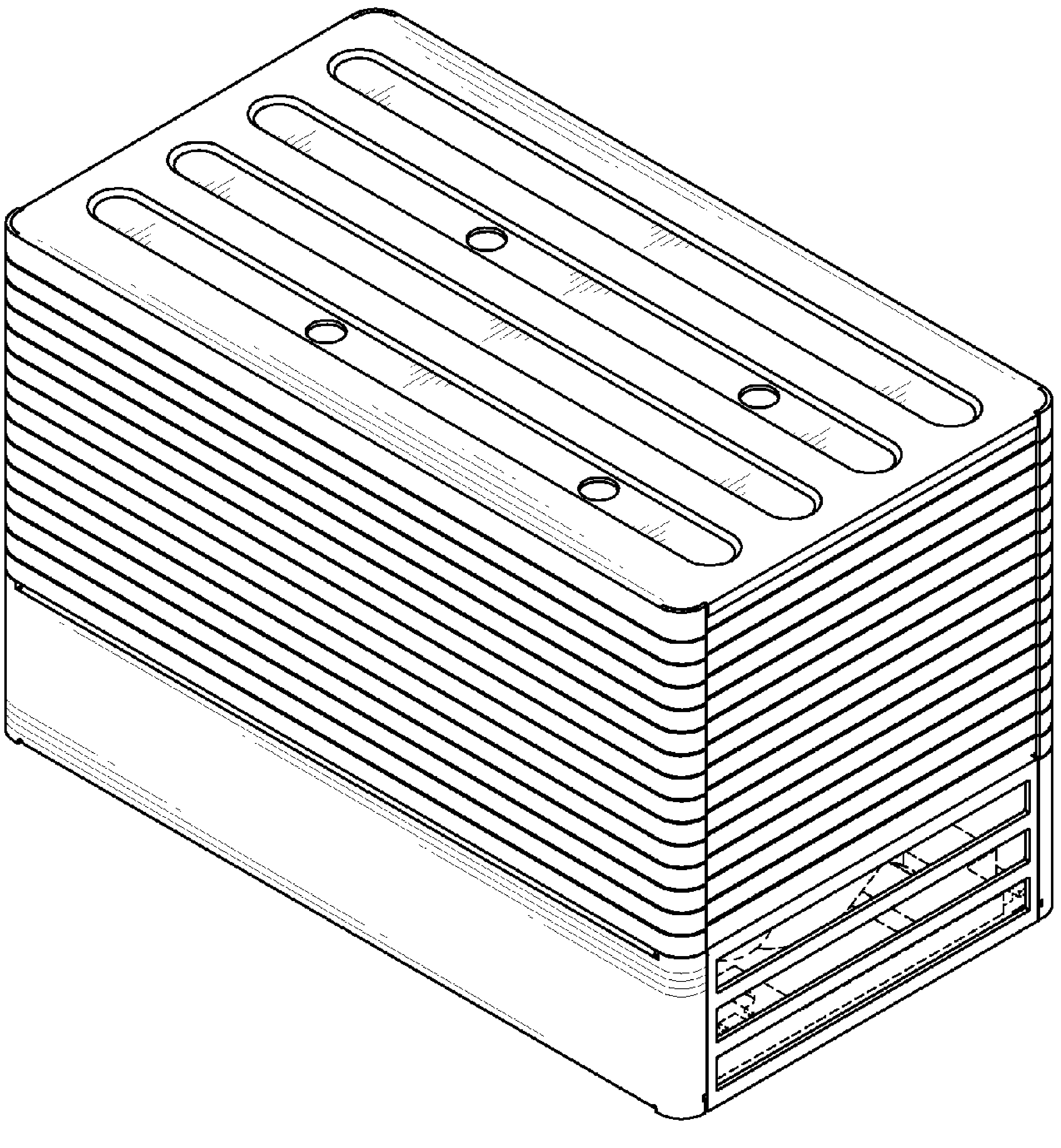
FIG. **5** is a right-side, elevational view thereof.

FIG. **6** is a top plan view thereof; and,

FIG. **7** is a bottom plan view thereof.

The broken lines shown in the figures are included for the purpose of illustrating portions of the heat dissipation device that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



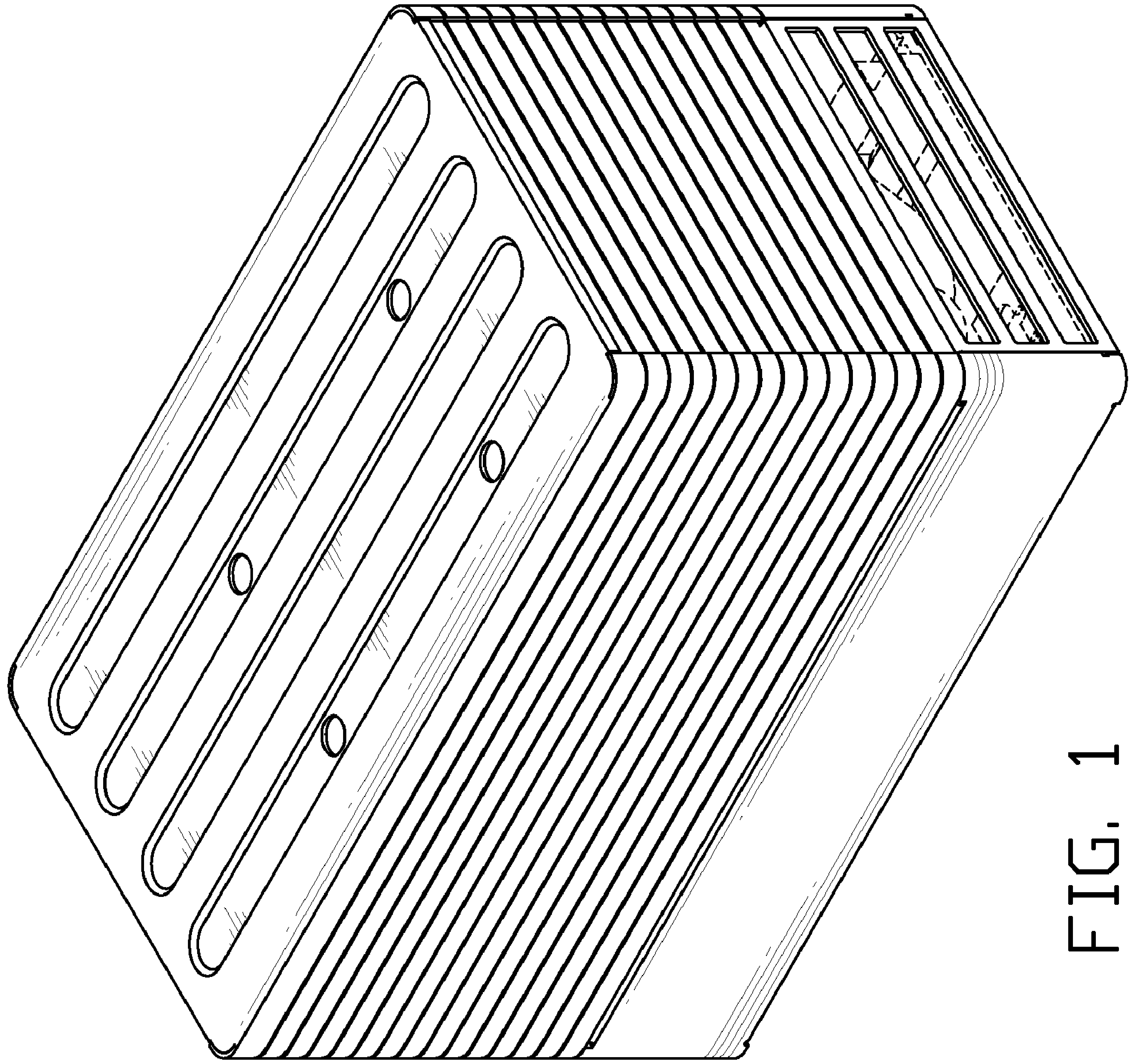


FIG. 1

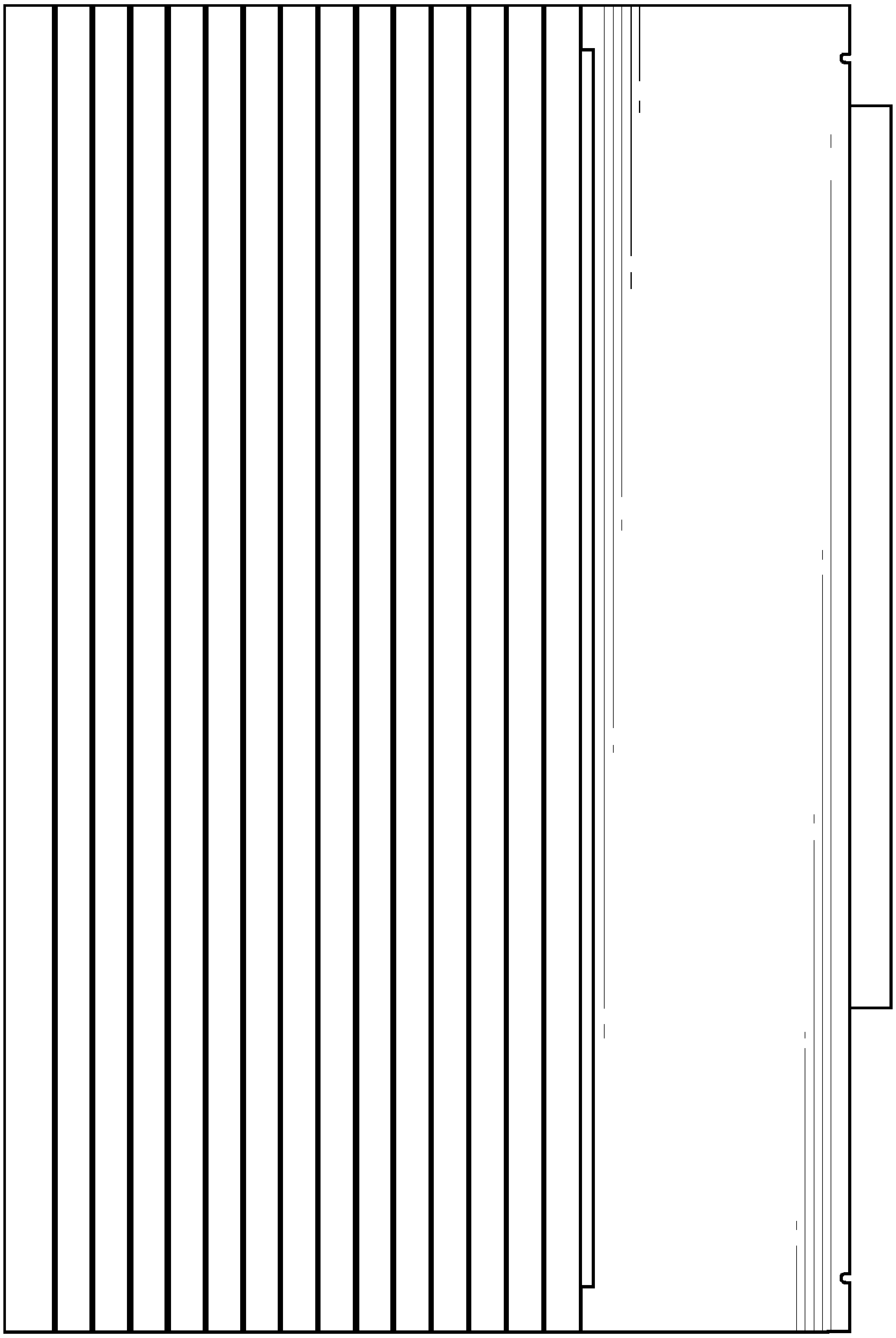


FIG. 2

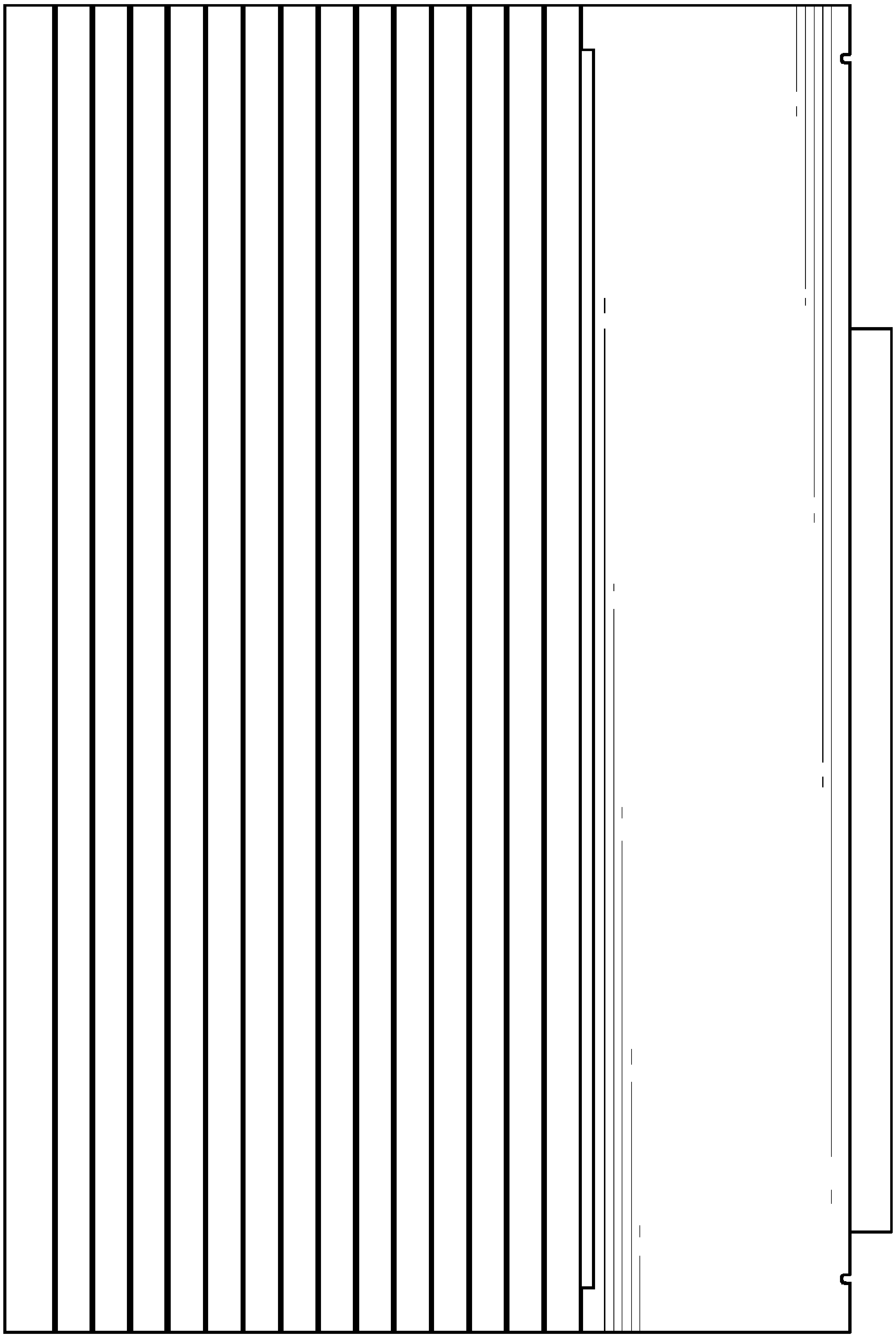


FIG. 3

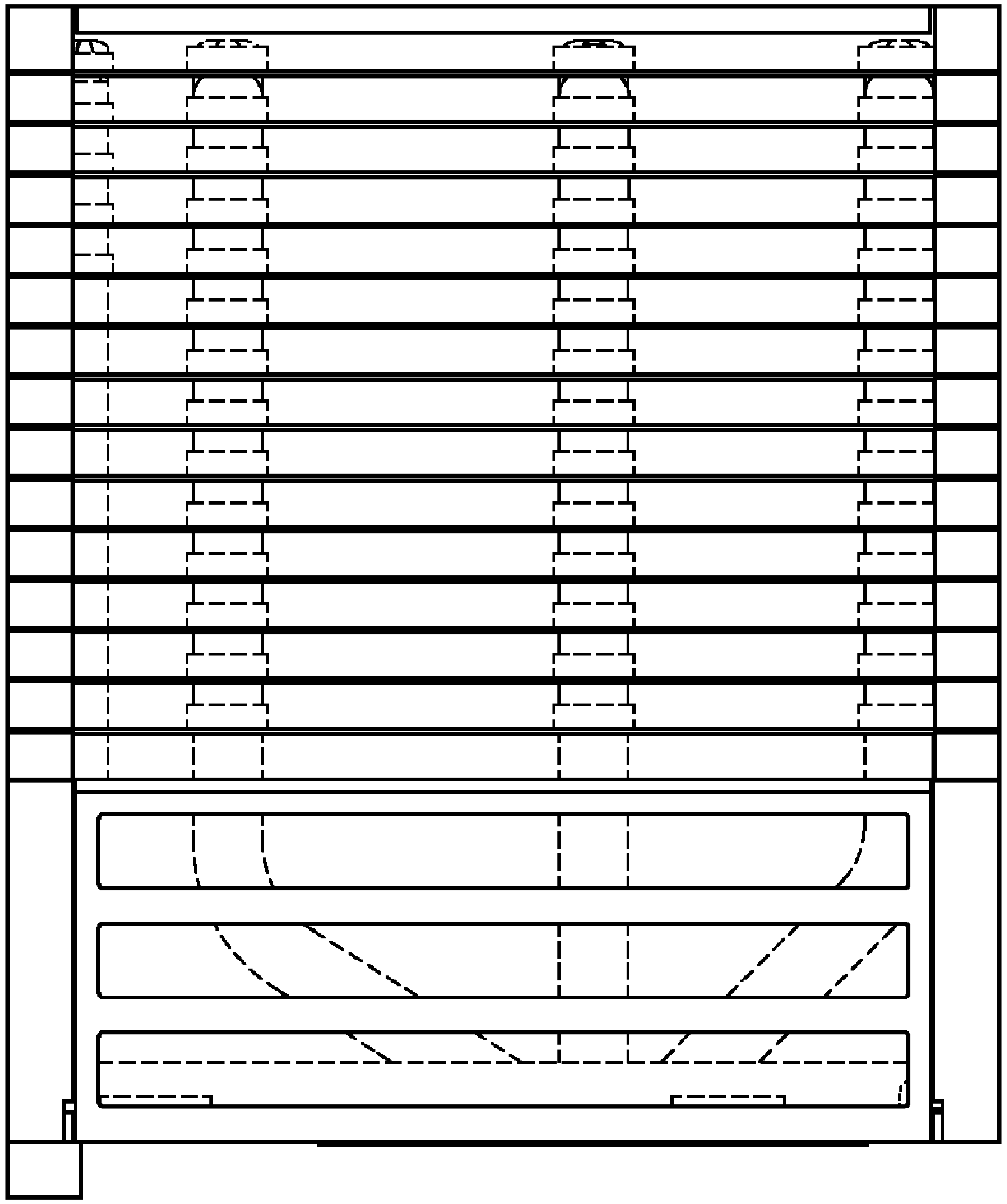


FIG. 4

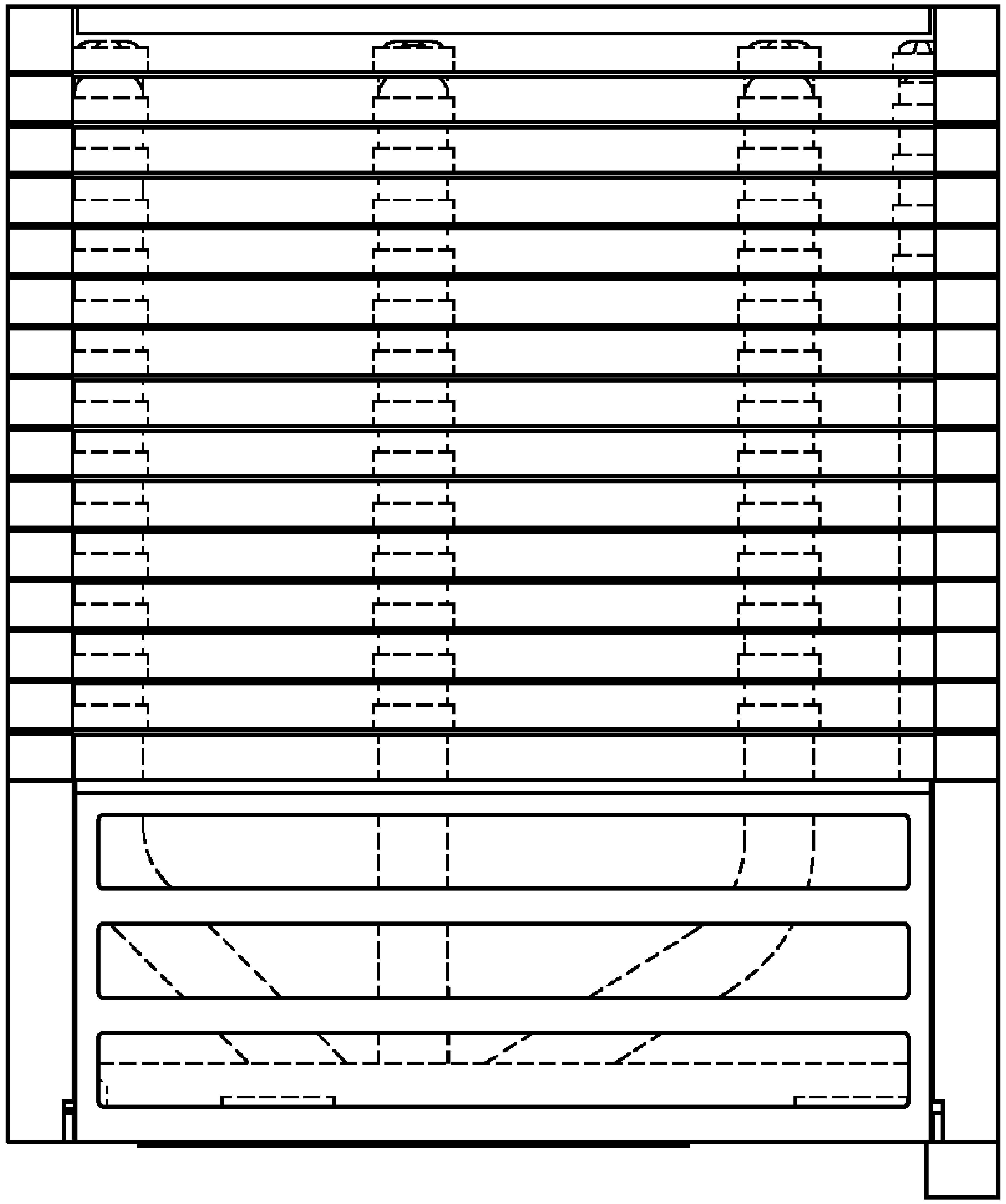


FIG. 5

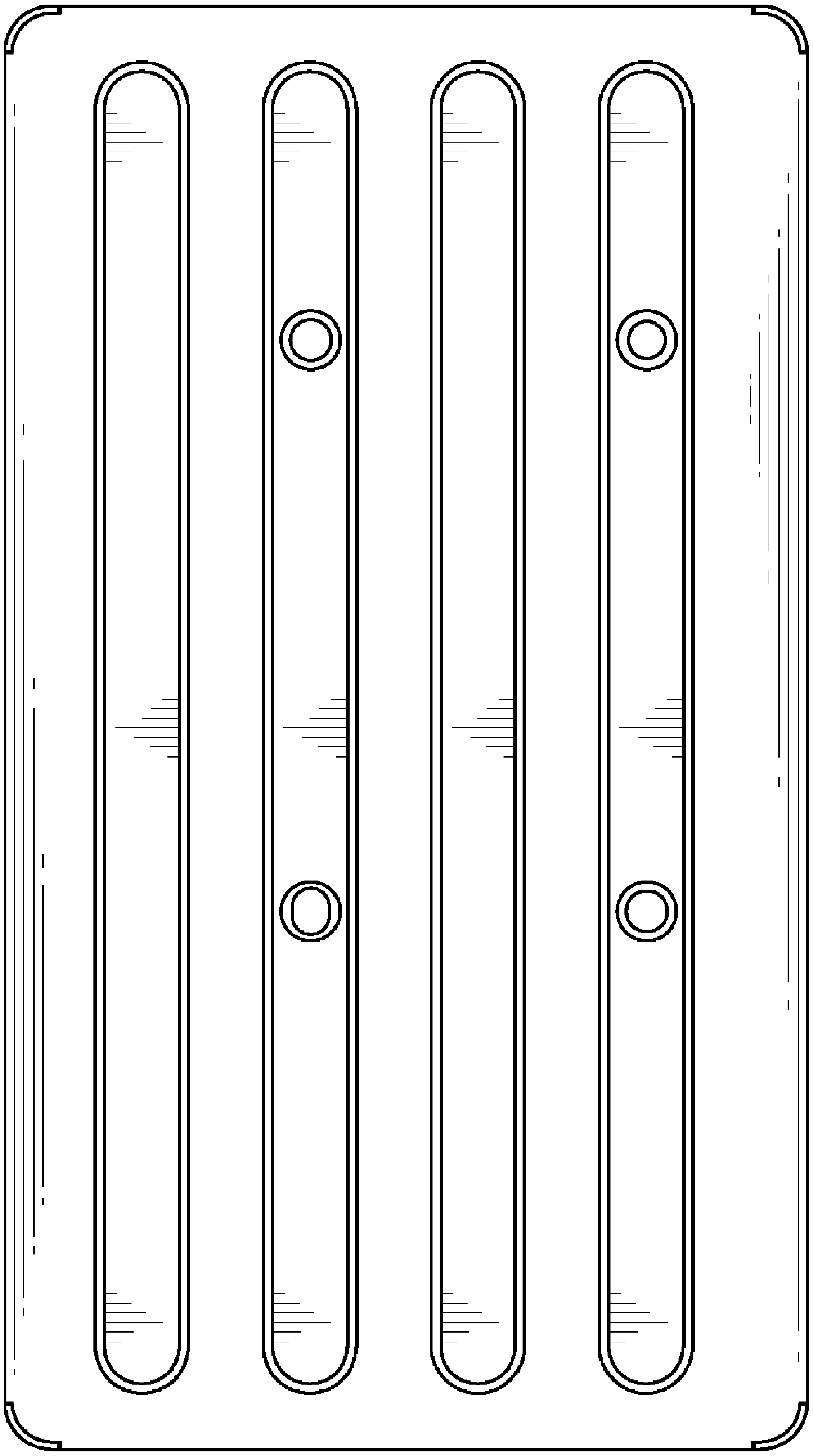


FIG. 6

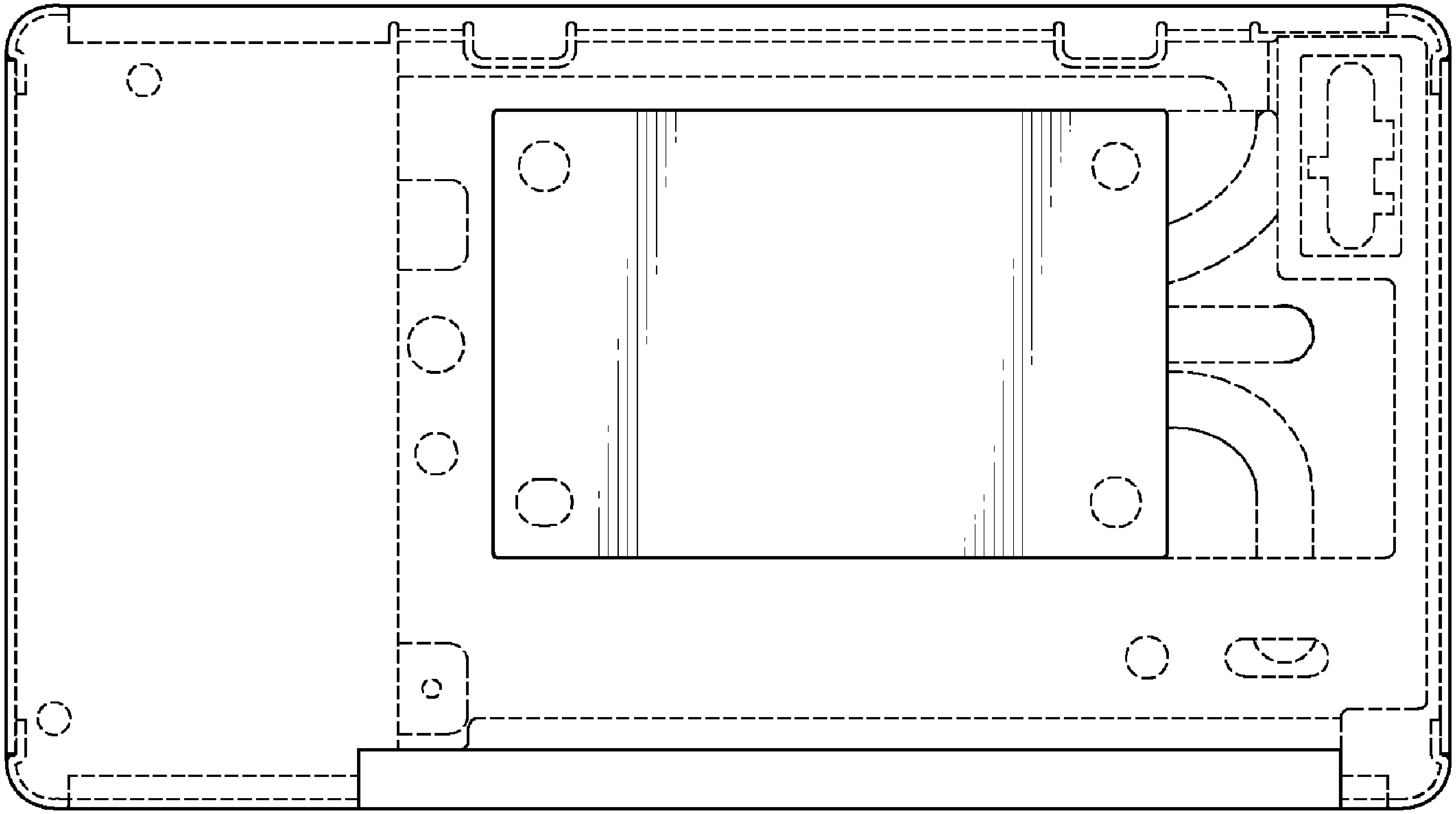


FIG. 7